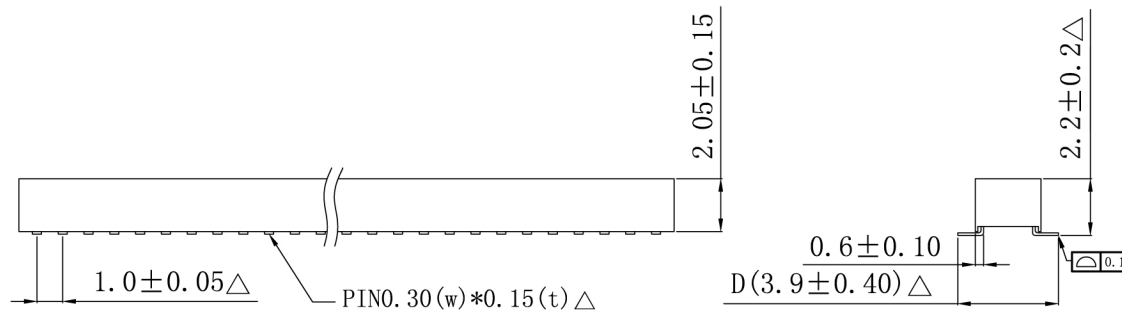


P. C. B SMT Layout



Specifications

Current Rating	:0.8 Amp
Insulator Resistance	:900 Megohms Min.
Contact Resistance	:20 m ohms max.
Dielectric Withstanding	:AC 500 V
Operating Temperature	:-40 °C ~ +105°C
Soldering Temperature	:260°C for 3~5sec Max.
Contact Material	:Phosphor Bronze
Insulator Material	:High Temperature Thermoplastic. UL 94V-0
Standard	:LCP
Finish	:Gold Plated
Standard	:Gold Flash all over

Series	Connector Type	Contact Plating	Material	Pin Length mm	Number of Contacts
F801	X	X	X	DXXX	-XX
(Female Header Dual Row) F801 (1.00 H:2.05 W:2.55)	M:SMT Type	G:Gold Flash T:Tin Plated A:10U°Gold B:15U°Gold C:20U°Gold ©Duplex Plating D:Gold Flash/Tin (Standard:G)	C:LCP (Standard:C)	M-D D039	(04 TO 80 Contacts)

所有材料為
"環保材料"

2014.12.22

RoHS

DESCRIPTION(內容):	DRAWN(製圖):	GENERAL TOLERANCE:(公差)	REV: A/2	REV	DESCRIPTION	DATE
1.00mm Female Header H:2.05 SMT	黃炳秋	X. ±0.30 X. ° ±5.0° .X ±0.20 .X ° ±3.0° .XX ±0.15 .XX ° ±1.0°	UNIT: mm	1	△此符號表示重點管控尺寸	2014.12.10
LCP	黃炳秋		SIZE: A4	2	修改P. C. B SMT Layout	2014.12.16
PART NO: (料號) F801-MGC-D039-XX	APPROVAL(核准):	SCALE(比例):	SHEET: 1/1	3		
DWG NO(圖號):	鄧文廣	XX:XX		4		